



Session Title:	[TuE2] Advanced Device and Processes
Session Date:	November 12 (Tue.), 2024
Session Time:	15:00-16:20
Session Room:	Room E (Sicily Room, 1F, Paradise Hotel Busan)
Session Chair:	Dr. Jean-Paul Booth (Inst. Polytechnique de Paris, France)

[TuE2-1] [Invited]

15:00-15:30

The Next Generation of Complementary FET (CFET) Etch Challenge and Progress

I. G. Koo, S. Choudhury, V. Brissonneau, E. Dupuy, H. Puliyalil, M. Hosseini, D. Batuk, C. Cavalcante, A. Vandooren, A. Veloso, L. P. B. Lima, S. Demuynck, N. Horiguchi, S. Biesemans, and F. Lazzarino (imec, Belgium)

[TuE2-2] [Invited]

15-30-16:00

Recent Trend and Challenge of Advanced Dry Etching Technology

Huichan Seo (SK hynix Inc., Korea)

[TuE2-3]

16:00-16:20

Selective Isotropic Atomic Layer Etching of Si_3N_4 over SiO_2 with Surface Fluorination Using $\text{CF}_4/\text{H}_2\text{O}$ Plasma and Thermal Heating

Daeun Hong, Hyeongwu Lee, Minsung Jeon, and Heeyeop Chae (Sungkyunkwan Univ., Korea)